L Number	Hits	Search Text	DB	Time stamp
1	2	(("5497545") or ("5654590")).PN.	USPAT	2002/12/24 17:39
2	1	("5965933").PN.	USPAT	2002/12/24 18:19
3	45	silicon near interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:20
4	45	(silicon near interposer) and (package or chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:32
5	5	438/977.ccls. and (pcb or pwb or (printed near board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:36
6	72	438/977.ccls. and (package or pcb or pwb or (printed near board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:36
7	67	(438/977.ccls. and (package or pcb or pwb or (printed near board))) not (438/977.ccls. and (pcb or pwb or (printed near board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:51
8	4174	(silicon near wafer) and (wafer near (thin$4 or remov$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:20
9	732	((silicon near wafer) and (wafer near (thin$4 or remov$4))) and (package or mount)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:53
10	1	(((silicon near wafer) and (wafer near (thin$4 or remov$4))) and (package or mount)) and sbp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:54
11	1	(((silicon near wafer) and (wafer near (thin$4 or remov$4))) and (package or mount)) and utsw	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:54
12	663	(((silicon near wafer) and (wafer near (thin$4 or remov$4))) and (package or mount)) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:59
13	84805	(silicon near (base or substrate or wafer)) and ((thin$4 or remov$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:31
14	1	("6423643").PN.	USPAT	2002/12/24 19:23
15	1	("5847458").PN.	USPAT	2002/12/24 19:24
16	1	("6411502").PN.	USPAT	2002/12/24 19:24
17	1	("6441502").PN.	USPAT	2002/12/24 19:25
18	1	("5900676").PN.	USPAT	2002/12/24 19:25
19	1	(("5847458").PN.) and (package or mount)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:27

20	8625	((silicon near (base or substrate or wafer)) and ((thin$4 or remov$4))) and (package or mount)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:27
21	4662	(((silicon near (base or substrate or wafer)) and ((thin$4 or remov$4))) and (package or mount)) and wafer	USPAT	2002/12/24 19:28
22	922	(((silicon near (base or substrate or wafer)) and ((thin$4 or remov$4))) and (package or mount)) and (holder or chuck)	USPAT	2002/12/24 19:29
23	1812	(((silicon near (base or substrate or wafer)) and ((thin$4 or remov$4))) and (package or mount)) and (holder or chuck or rigid)	USPAT	2002/12/24 19:29
24	3	utsw	USPAT	2002/12/24 19:30
25	7	utsw	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:30
26	1168	sbp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:31
27	686	sbp and (thin$4 or remov$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:32
28	81	sbp and ((thin$4 or remov$4 or etch or planar$4) with (silicon or wafer or base or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:47
29	33206	(thin$4 or remov$4 or etch or planar$4) near base	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:49
30	49285	(thin$4 or remov$4 or etch or planar$4) near (base or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:50
31	5561	((thin$4 or remov$4 or etch or planar$4) near (base or wafer)) and (silicon near (base or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:51
32	64	(((thin$4 or remov$4 or etch or planar$4) near (base or wafer)) and (silicon near (base or wafer))) and (pcb or pwb or (printed near board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:54
33	317	(((thin$4 or remov$4 or etch or planar$4) near (base or wafer)) and (silicon near (base or wafer))) and ((chip or die)with (package or mount))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:55
34	317	(((thin$4 or remov$4 or etch or planar$4) near (base or wafer)) and (silicon near (base or wafer))) and ((chip or die) with (package or mount))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:18
35	661	438/for.340.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:18

36	661	438/for.340.ccls. and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:33
37	0	438/106.ccls and (thin$4 or remov$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:32
38	1165	438/106.ccls. and (thin$4 or remov$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:34
39	1033	(438/106.ccls. and (thin$4 or remov$3)) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:34
40	73	438/106.ccls. and ((thin$4 or remov$3) near (silicon or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:40
41	29	438/108.ccls. and ((thin$4 or remov$3) near (silicon or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:45
42	0	6420209.URPN.	USPAT	2002/12/24 20:42
43	0	6420209.URPN.	USPAT	2002/12/24 20:42
44	20	438/668.ccls. and ((thin$4 or remov$3) near (silicon or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:48
45	52	257/777.ccls. and ((thin$4 or remov$3) near (silicon or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:57
46	1229	((ball or bump or connect$3) near wafer) and (chip or die or package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:59
47	1059	(((ball or bump or connect$3) near wafer) and (chip or die or package)) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 21:29
48	204	silicon with interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 21:31